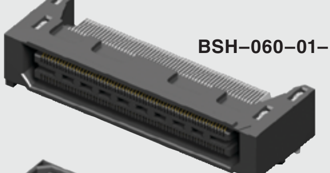
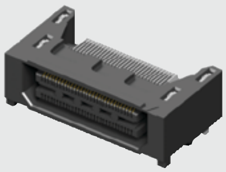
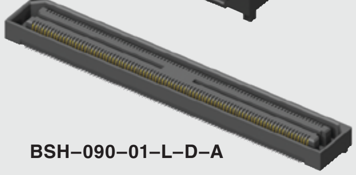
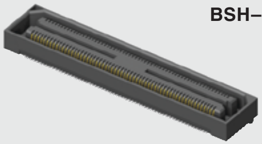
samtec


BSH–060–01–F–D–RA–WT


BSH–030–01–L–D–RA–WT

10 YEAR MFG WITH 50 µ" GOLD
EXTENDED LIFE PRODUCT
HIGH MATING CYCLES


BSH–090–01–L–D–A


BSH–060–01–F–D–A

(0.50 mm) .0197"

BSH SERIES

BASIC BLADE & BEAM SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?BSH

Insulator Material:
Black LCP
Contact Material:
Phosphor Bronze
Plating:
Au or Sn over
50 µ" (1.27 µm) Ni
Current Rating:
2 A per pin
(2 pins powered)
Flammability Rating:
UL 94 VO
Operating Temp Range:
-55 °C to +125 °C
Voltage Rating:
175 VAC
Max Cycles:
100
RoHS Compliant:
Yes

PROCESSING

Lead-Free Solderable:
Yes
SMT Lead Coplanarity:
(0.10 mm) .004" max (030-090)
(0.15 mm) .006" max (120-150)*
*(.004" stencil solution may be available; contact IPG@samtec.com)
Board Stacking:
For applications requiring more than two connectors per board or 90 positions or higher, contact ipg@samtec.com

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality

FILE NO. E111594

ALSO AVAILABLE
(MOQ Required)

- 30 µ" (0.76 µm) Gold
- Edge Mount Capability
- 8 mm, 11 mm, 16 mm, 19 mm and 22 mm Stack Height (Caution: Some automatic placement/ inspection machines may have component height restrictions. Please consult machinery specifications.) (11 mm, 16 mm, 19 mm and 22 mm not available with 50 positions)

Note:
Some lengths, styles and options are non-standard, non-returnable.

BSH – NO. OF POSITIONS PER ROW – 01 – PLATING OPTION – D – A – OTHER OPTION

Mates with:
BTH

–030, –050, –060, –090, –120, –150

PLATING OPTION:

–F
= Gold Flash on contact, Matte Tin on tail

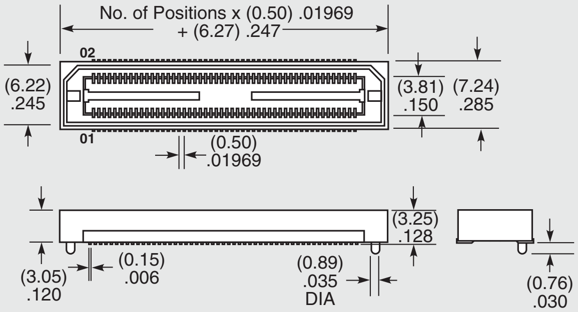
–L
= 10 µ" (0.25 µm) Gold on contact, Matte Tin on tail

–C*
= Electro-Polished Selective 50 µ" (1.27 µm) min Au over 150 µ" (3.81 µm) Ni on Signal Pins in contact area, Matte Tin over 50 µ" (1.27 µm) min Ni on all solder tails

***Note:** –C Plating passes 10 year MFG testing

OTHER OPTION:

–TR
= Tape & Reel (120 positions maximum)

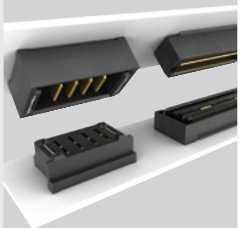


MATED HEIGHT

LEAD STYLE	MATED HEIGHT*
–01	(5.00) .197

*Processing conditions will affect mated height.

POWER/SIGNAL APPLICATION



Compatible with UMPT/UMPS for flexible two-piece power/signal solutions

BSH – NO. OF POSITIONS PER ROW – 01 – PLATING OPTION – D – RA – WT – OTHER OPTION

Mates with:
BTH

–030, –060, –090

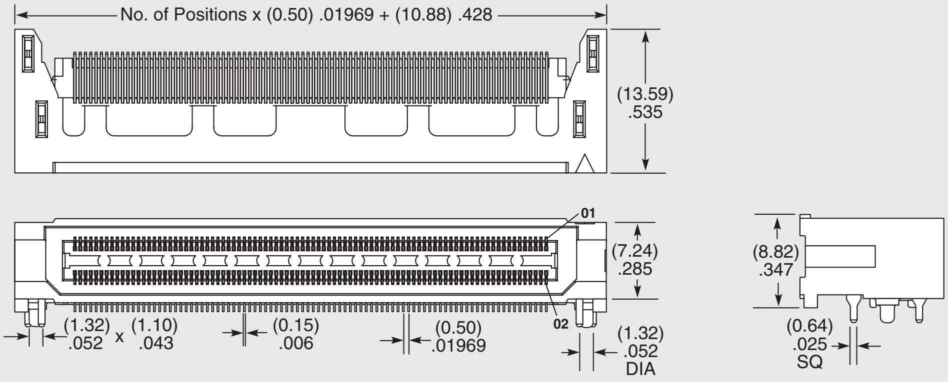
PLATING OPTION:

–F
= Gold Flash on contact, Matte Tin on tail

–L
= 10 µ" (0.25 µm) Gold on contact, Matte Tin on tail

OTHER OPTION:

–GP
= Guide Post



Due to technical progress, all designs, specifications and components are subject to change without notice.

All parts within this catalog are built to Samtec's specifications.
irements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.